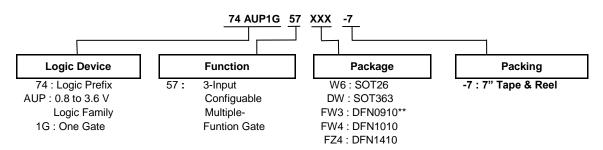


## **Ordering Information**



Davies	Package	Package	Package	7" Tape a	nd Reel
Device	Code	(Notes 4 & 5)	Size	Quantity	Part Number Suffix
74AUP1G57W6-7	W6	SOT26	3.0mm x 2.8mm x 1.2mm 0.95 mm lead pitch	3,000/Tape & Reel	-7
74AUP1G57DW-7	DW	SOT363	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74AUP1G57FW3-7**	FW3	X2-DFN0910-6	0.9mm x 1.0mm x 0.35mm 0.3 mm lead pitch	5,000/Tape & Reel	-7
74AUP1G57FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm lead pitch	5,000/Tape & Reel	-7
74AUP1G57FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm lead pitch	5,000/Tape & Reel	-7

Notes:

- 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 5. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.
  \*\* The X2-DFN0910-6 is a future product.

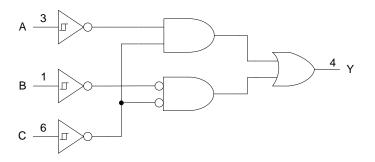
## **Pin Descriptions**

Pin Name	Function
В	Data Input
GND	Ground
А	Data Input
Υ	Data Output
V <sub>CC</sub>	Supply Voltage
С	Data Input

### **Function Table**

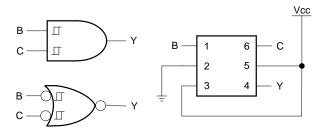
	Inputs		Output
С	В	Α	Y
L	L	L	Н
L	L	Н	L
L	Н	L	Н
L	Н	Н	L
Н	L	L	L
Н	L	Н	L
Н	Н	L	Н
Н	Н	Н	Н

# **Logic Diagram**

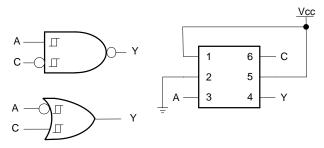




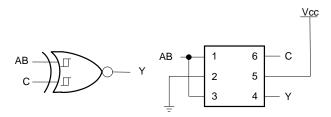
## **Logic Configurations**



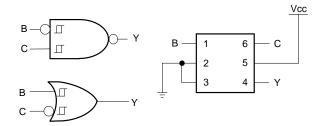
Configuration 1
2-Input AND Gate
2-Input NOR Gate with Both Inputs Inverted



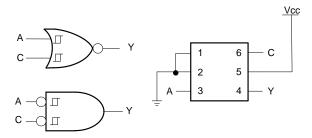
Configuration 3
2-Input NAND Gate with C Input Inverted
2-Input OR Gate with A Input Inverted



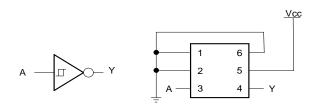
Configuration 5 2-Input XNOR Gate



Configuration 2 2-Input NAND Gate with B Input Inverted 2-Input OR Gate with C input Inverted



Configuration 4
2-Input NOR Gate
2-Input AND Gate with Both Inputs Inverted



Configuration 6 Inverter

Function Selection Table	
Logic Function	Configuration
2-Input AND	1
2-Input AND with both inputs inverted	4
2-Input NAND with inverted input	2, 3
2-Input OR with inverted input	2, 3
2-Input NOR	4
2-Input NOR with both inputs inverted	1
2-Input XNOR	5
1-Input INVERTER	6

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## Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +4.6	V
VI	Input Voltage Range	-0.5 to +4.6	V
Vo	Voltage applied to output in high or low state	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-50	mA
lok	Output Clamp Current (V <sub>O</sub> < 0)	-50	mA
lo	Continuous Output Current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±20	mA
Icc	Continuous Current through V <sub>CC</sub>	50	mA
I <sub>GND</sub>	Continuous Current through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes:

- 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

## **Recommended Operating Conditions** (Note 8)

Symbol		Parameter	Min	Max	Unit
V <sub>CC</sub>	Operating Voltage		0.8	3.6	V
VI	Input Voltage		0	3.6	V
\/	Output Valtage	Active Mode	0	Vcc	V
Vo	Output Voltage	Power Down Mode	0	3.6	V
		V <sub>CC</sub> = 0.8 V	-	-20	μA
	I <sub>OH</sub> High-Level Output Current	V <sub>CC</sub> = 1.1 V	-	-1.1	
		V <sub>CC</sub> = 1.4 V	-	-1.7	
ЮН		V <sub>CC</sub> = 1.65 V	-	-1.9	mA
		V <sub>CC</sub> = 2.3 V	-	-3.1	
		V <sub>CC</sub> = 3.0 V	-	-4	
		V <sub>CC</sub> = 0.8 V	-	20	uA
		V <sub>CC</sub> = 1.1 V	-	1.1	
		V <sub>CC</sub> = 1.4 V	-	1.7	
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 1.65 V	-	1.9	mA
		V <sub>CC</sub> = 2.3 V	-	3.1	
		V <sub>CC</sub> = 3.0 V	-	4	
TA	Operating Free-Air Temperature	-	-40	+125	°C

Note: 8. Unused inputs should be held at Vcc or Ground.



## **Electrical Characteristics**

	_			T <sub>A</sub> = -	+25°C	T <sub>A</sub> =-40	to +85°C	
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
		-	0.8V	0.3	0.65	0.3	0.7	
	Booitive Coina	-	1.1V	0.53	0.9	0.53	0.9	
.,	Positive-Going	-	1.4V	0.74	1.11	0.74	1.11	V
$V_{T+}$	Input Threshold	-	1.65V	0.91	1.29	0.91	1.29	V
	Voltage	-	2.3V	1.37	1.77	1.37	1.77	
		=	3.0V	1.88	2.29	1.88	2.29	
		-	0.8V	0.1	0.6	0.1	0.6	
	Negative-Going	=	1.1V	0.26	0.65	0.26	0.65	
$V_{T-}$	Input Threshold	-	1.4V	0.39	0.75	0.39	0.75	V
• 1-	Voltage	-	1.65V	0.47	0.84	0.47	0.84	
	Voltage	-	2.3V	0.69	1.04	0.69	1.04	
		-	3.0V	0.88	1.24	0.88	1.24	
		=	0.8V	0.07	0.5	0.07	0.5	_
		-	1.1V	0.08	0.46	0.08	0.46	_
$\Delta V_T$	Hysteresis	-	1.4V	0.18	0.56	0.18	0.56	V
·	(V <sub>T+</sub> - V <sub>T-)</sub>	=	1.65V	0.27	0.66	0.27	0.66	<u> </u>
		-	2.3V	0.53	0.92	0.53	0.92	4
		-	3.0V	0.79	1.31	0.79	1.31	
		I <sub>OH</sub> = -20μA	0.8V to 3.6V	V <sub>CC</sub> – 0.1	-	V <sub>CC</sub> – 0.1	-	_
		I <sub>OH</sub> = -1.1mA	1.1V	0.75 x V <sub>CC</sub>	-	0.7 x V <sub>CC</sub>	-	
		$I_{OH} = -1.7 \text{mA}$	1.4V	1.11	ı	1.03	-	
	High-Level Output Voltage	$I_{OH} = -1.9 \text{mA}$	1.65V	1.32	-	1.3	-	.,
		I <sub>OH</sub> = -2.3mA		2.05	-	1.97	-	V
		I <sub>OH</sub> = -3.1mA	2.3V	1.9	-	1.85	-	
		I <sub>OH</sub> = -2.7mA	2) /	2.72	=	2.67	-	1
		I <sub>OH</sub> = -4mA	3V	2.6	-	2.55	-	
		I <sub>OL</sub> = 20μA	0.8V to 3.6V	-	0.1	-	0.1	
		I <sub>OL</sub> = 1.1mA	1.1V	-	0.3 x V <sub>CC</sub>	-	0.3 x V <sub>CC</sub>	
		I <sub>OL</sub> = 1.7mA	1.4V	-	0.31	-	0.37	
.,	Low-Level Input	I <sub>OL</sub> = 1.9mA	1.65 V	-	0.31	-	0.35	V
$V_{OL}$	Voltage	$I_{OL} = 2.3 \text{mA}$	0.01/		0.31	-	0.33	v
		I <sub>OL</sub> = 3.1mA	2.3V	-	0.44	-	0.45	
		I <sub>OL</sub> = 2.7mA		_	0.31	-	0.33	
			3V		0.44	_	0.45	
		I <sub>OL</sub> = 4mA			0.44	-	0.45	
II	Input Current	A or B Input V <sub>I</sub> =GND to 3.6 V	0V to 3.6V	-	± 0.1	-	± 0.5	μA
l <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 =$ 0V to 3.6V	0	-	± 0.2	-	± 0.6	μΑ
$\Delta I_{OFF}$	Delta Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0V to 0.2 V	-	± 0.2	-	± 0.6	μA
I <sub>CC</sub>	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_{O}=0$	0.8V to 3.6V	-	0.5	-	0.9	μА
ΔI <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> – 0.6 V Other inputs at V <sub>CC</sub> or GND	3.3V	-	40	-	50	μA



## **Electrical Characteristics** (continued)

Completed	Danamata	Took Compiler	V	T <sub>A</sub> =-40 t	to +125°C	Unit
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Unit
		-	0.8V	0.3	0.7	
	Positive-Going	=	1.1V	0.53	0.92	
\ /	Input	-	1.4V	0.74	1.13	V
$V_{T+}$	Threshold	-	1.65V	0.91	1.31	v
	Voltage	-	2.3V	1.37	1.8	
		-	3.0V	1.88	2.32	
		-	0.8V	0.1	0.6	
	Negative-	-	1.1V	0.26	0.65	
$V_{T-}$	Going Input	-	1.4V	0.39	0.75	V
• 1-	Threshold	-	1.65V	0.47	0.84	
	Voltage	-	2.3V	0.69	1.04	
		-	3.0V	0.88	1.24	
		-	V8.0	0.07	0.5	
		-	1.1V	0.08	0.46	
$\Delta V_T$	Hysteresis	-	1.4V	0.18	0.56	V
•	(V <sub>T+</sub> - V <sub>T-)</sub>	-	1.65V	0.27	0.66	
		=	2.3V	0.53	0.92	
		-	3.0V	0.79	1.31	
		I <sub>OH</sub> = -20μA	0.8V to 3.6V	V <sub>CC</sub> – 0.11	-	
		I <sub>OH</sub> = -1.1mA	1.1V	0.6 x V <sub>CC</sub>	-	
VoH		$I_{OH} = -1.7 \text{mA}$	1.4V	1.4V 0.93 -		
	High-Level	I <sub>OH</sub> = -1.9mA	1.65V	1.17	-	.,
	Output Voltage	I <sub>OH</sub> = -2.3mA		1.77	-	V
	Voltage	I <sub>OH</sub> = -3.1mA	2.3V	1.67	-	
Volta				2.40	_	
		I <sub>OH</sub> = -2.7mA	3V		_	
		I <sub>OH</sub> = -4mA	2.01/	2.30		
		$I_{OL} = 20\mu A$	0.8V to 3.6V	-	0.11	
		$I_{OL} = 1.1 \text{mA}$	1.1V	-	0.33 x V <sub>CC</sub>	
		$I_{OL} = 1.7 \text{mA}$	1.4V	-	0.41	
	Low-Level	I <sub>OL</sub> = 1.9mA	1.65 V	-	0.39	١
$V_{OL}$	Input Voltage	I <sub>OL</sub> = 2.3mA		-	0.36	V
		I <sub>OL</sub> = 3.1mA	2.3V	_	0.50	
				_	0.36	
		$I_{OL} = 2.7 \text{mA}$	3V			
		I <sub>OL</sub> = 4mA			0.50	
lı	Input Current	A or B Input V <sub>I</sub> =GND to 3.6 V	0V to 3.6V	-	± 0.75	μΑ
l <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0	-	± 1.0	μA
$\Delta I_{OFF}$	Delta Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0V to 0.2 V	-	± 2.5	μA
I <sub>CC</sub>	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_O=0$	0.8V to 3.6V	-	1.4	μA
ΔI <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> – 0.6 V Other inputs at V <sub>CC</sub> or GND	3.3V	-	75	μA



## **Package Characteristics**

Symbol	Parameter	Package	Test Conditions	Min	Тур.	Max	Unit
		SOT26		-	166	-	
θιΔ Ι		SOT363		-	371	-	
	Thermal Resistance Junction-	X2-DFN0910-6	(Note 9)	-	450	-	°C/W
	to-Ambient	X2-DFN1010-6	, , ,	-	445	-	
		X2-DFN1410-6		-	430	-	
		SOT26		-	46	-	
		SOT363		-	143	-	
$\theta_{JC}$	Thermal Resistance Junction-	X2-DFN0910-6	(Note 9)	-	255	-	°C/W
	to-Case	X2-DFN1010-6	, ,	-	250	-	1
		X2-DFN1410-6		-	190	-	

Note: 9. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

## **Operating Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Р	arameter	Test Conditions	Vcc	TYP	Unit	
			0.8 V	4		
	Power Dissipation		1.2V ± 0.1V	4	1	
_		f = 1MHz	1.5V ± 0.1V	4	pF	
$C_{pd}$		No Load	1.8V ± 0.15V	4		
	Capacitance		2.5V ± 0.2V	4.4		
			$3.3 \pm 0.3 \text{V}$	4.8		
Cı	Input Capacitance	V <sub>i</sub> = V <sub>CC</sub> or GND	0 V or 3.3V	1.1	pF	
Co	Output Capacitance	V <sub>0</sub> = V <sub>CC</sub> or GND	0 V	2.0	pF	

# **Switching Characteristics**

C<sub>L</sub>=5pF, See Figure 1

Parameter	From	TO OUTPUT	Vaa	10		C to +85°C	T <sub>A</sub> = -40°C 1	to +125°C	Unit		
rarameter	Input			Min	Max	Min	Max	Unit			
A,			0.8 V	-	28	-	-	-	-	ı	
	A,		1.2 V ± 0.1 V	2.6	7.4	14.4	2.1	14.8	2.1	15.1	
t <sub>e d</sub>	В,	B, or C	1.5 V ± 0.1 V	1.9	4.6	7.6	1.4	8.2	1.4	8.6	ns
			1.8 V ± 0.15 V	1.4	3.9	6.2	0.9	6.8	0.9	7.2	113
	С		2.5 V ± 0.2 V	1.1	3.1	4.5	0.6	5.1	0.6	5.3	
			3.3 V ± 0.3 V	1	2.8	3.9	0.5	4.1	0.5	4.3	



# Switching Characteristics (continued)

C<sub>L</sub>=10pF, See Figure 1

Danamatan	From	то	.,	7	Γ <sub>A</sub> = +25°C		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			+125ºC	l lmit
Parameter	Input	OUTPUT	V <sub>CC</sub>	Min	TYP	Max	Min	Max	Min	Max	Unit
			0.8 V	=	32	-	-	-	-	-	
	A,		1.2 V ± 0.1 V	2.6	8.3	16.4	2.1	17	2.1	17.3	
	В,		1.5 V ± 0.1 V	1.9	5.2	8.7	1.4	9.4	1.4	9.8	]
t <sub>pd</sub>	or	Ť	1.8 V ± 0.15 V	1.4	4.5	7	0.9	7.8	0.9	8.2	ns
	С		2.5 V ± 0.2 V	1.1	3.7	5.2	0.6	5.9	0.6	6.2	
			3.3 V ± 0.3 V	1	3.4	4.6	0.5	4.9	0.5	5.1	

C<sub>L</sub>=15pF, See Figure 1

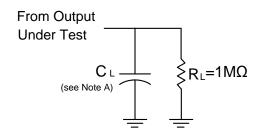
Bonometer From		то	то	то	то		T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		1111
Parameter Input (	OUTPUT	PUT V <sub>CC</sub>	Min	TYP	Max	Min	Max	Min	Max	Unit			
		A, B, or C	0.8 V	-	38	-	-	-	-	-			
	A,		1.2 V ± 0.1 V	3.4	9.1	17.9	3.1	19.8	3.1	20			
	В,		1.5 V ± 0.1 V	2.8	5.7	9.6	2.3	10.4	2.3	10.9	200		
t <sub>pd</sub>	or		1.8 V ± 0.15 V	2.1	4.9	7.8	1.6	8.7	1.6	9.2	ns		
	С		2.5 V ± 0.2 V	1.7	4.1	5.8	1.2	6.5	1.2	6.9			
			3.3 V ± 0.3 V	1.5	3.8	5.1	1	5.5	1	5.7			

C<sub>L</sub>=30pF, See Figure 1

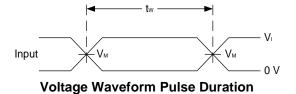
Barratas From		TO OUTPUT	то	.,	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		l lmi4
Parameter Input	Vcc		Min	TYP	Max	Min	Max	Min	Max	Unit	
			0.8 V	=	46	-	-	-	-	-	
	Α,	A, B, or C	1.2 V ± 0.1 V	4.6	11.9	23.8	3.9	24.9	3.9	25.4	
			1.5 V ± 0.1 V	3.6	7.4	12.2	3.4	13.3	3.4	14.1	200
t <sub>pd</sub>	or		1.8 V ± 0.15 V	3.1	6.2	9.9	2.6	11.1	2.6	11.8	ns
	С		2.5 V ± 0.2 V	2.6	5.2	7.4	2.1	8.3	2.1	8.8	
			3.3 V ± 0.3 V	2.3	4.9	6.6	1.8	7	1	7.4	

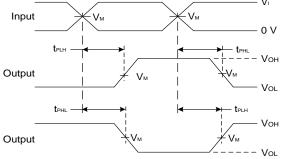


## **Parameter Measurement Information**



V <sub>CC</sub>	Inputs		$V_{M}$	Cı	
	Vı	t <sub>r</sub> /t <sub>f</sub>	<del></del>		
0.8 V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	
1.2V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	
1.5V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	
1.8V±0.15V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	
2.5V±0.2V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	
3.3V±0.3V	Vcc	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30 pF	





**Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs** 

Figure 1. Load Circuit and Voltage Waveforms

- A. Includes test lead and test apparatus capacitance.B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD</sub>.

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### **Marking Information**

(1) SOT26, SOT363

5 4 XX Y W X 1 2 3

74AUP1G57W6

74AUP1G57DW

XX: Identification code

Y: Year 0~9

W: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

AP

ΒV

52 and 53 week X: A~Z: Internal Code

Part Number	Package	Identification Code

SOT26

SOT363

### (2) X2-DFN0910-6, X2-DFN1010-6, X2-DFN1410-6

(Top View)

XX  $\underline{\mathsf{XX}}$  : Identification Code

 $\overline{Y}$  : Year : 0~9

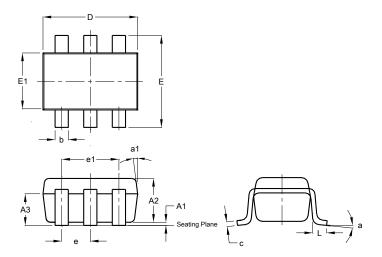
Week: A~Z: 1~26 week;
 a~z: 27~52 week; z represents

52 and 53 week X: A~Z: Internal code

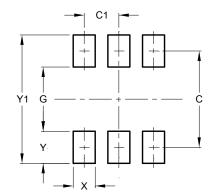
Part Number	Package	Identification Code
74AUP1G57FW3	X2-DFN0910-6	AP
74AUP1G57FW4	X2-DFN1010-6	BV
74AUP1G57FZ4	X2-DFN1410-6	NG



# SOT26 Package Outline Dimensions and Suggested Pad Layout



	SC	DT26	
Dim	Min	Max	Тур
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
С	0.10	0.20	0.15
D	2.90	3.10	3.00
е	-	-	0.95
e1	-	-	1.90
Е	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
а	-	-	8°
a1	-	-	7°
All	Dimen	sions	in mm

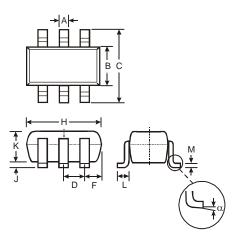


Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20

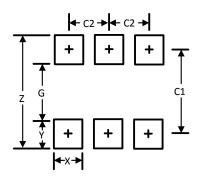


## SOT363 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SOT363						
Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D		0.65 Ty	p				
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
J	0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.22	0.11				
α	0°	8°	-				
All	Dimen	sions i	n mm				

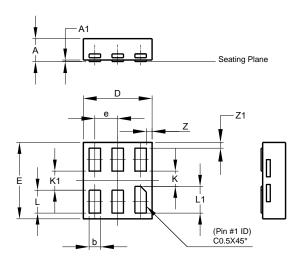


Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65

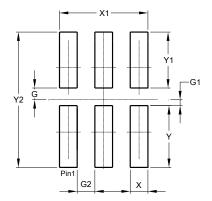
Downloaded from **Arrow.com**.



# X2-DFN0910-6 Package Outline Dimensions and Suggested Pad Layout



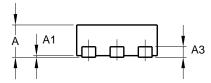
	X2-DFN0910-6					
Dim	Min	Max	Тур			
Α	ı	0.35	0.30			
A1	0	0.03	0.02			
b	0.10	0.20	0.15			
D	0.85	0.95	0.90			
Е	0.95	1.05	1.00			
е	ı	-	0.30			
K	0.20	-	-			
K1	0.25	-	-			
L	0.25	0.35	0.30			
L1	0.30	0.40	0.35			
Z	-	-	0.075			
<b>Z</b> 1	-	-	0.075			
All	Dimensi	ons in	mm			

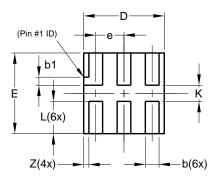


Dimensions	Value (in mm)
G	0.100
G1	0.050
G2	0.150
X	0.150
X1	0.750
Y	0.525
Y1	0.475
Y2	1.150

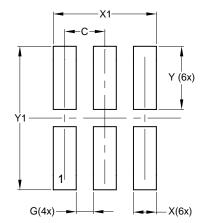


# X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout





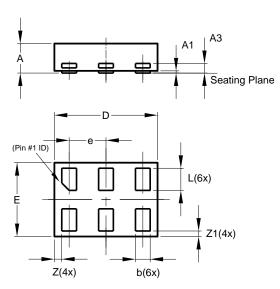
	X2-DFN	I1010-6	
Dim	Min	Max	Тур
Α		0.40	0.39
A1	0.00	0.05	0.02
A3			0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
Е	0.95	1.05	1.00
е			0.35
L	0.35	0.45	0.40
K	0.15	_	
Z			0.065
All I	Dimens	ions in	mm



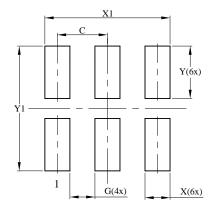
Dimensions	Value (in mm)
С	0.350
G	0.150
Х	0.200
X1	0.900
Y	0.550
V1	1 250



# X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout



	X2-DFN1410-6				
Dim	Min	Max	Тур		
Α		0.40	0.39		
A1	0.00	0.05	0.02		
A3			0.13		
b	0.15	0.25	0.20		
D	1.35	1.45	1.40		
Е	0.95	1.05	1.00		
е			0.50		
L	0.25	0.35	0.30		
Ζ			0.10		
<b>Z</b> 1	0.045	0.105	0.075		
All Dimensions in mm					



Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
Y1	1.250



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